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(12) **United States Design Patent**  
**Cai**

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(54) **LIGHT EMITTING DIODE PACKAGE**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/180**

(58) **Field of Classification Search**

CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;  
H01L 27/156; H01L 31/02; H01L 33/00;  
H01L 33/04; H01L 33/08; H01L 33/10;  
H01L 33/20; H01L 33/38; H01L 33/42;  
H01L 33/4862; H01L 33/483; H01L 33/486  
USPC ..... D13/180; D26/1; 257/79, 80, 81, 88,  
257/89, 95, 98, 99, 100, E33.058; 313/483,  
313/498, 500; 362/555, 800

See application file for complete search history.

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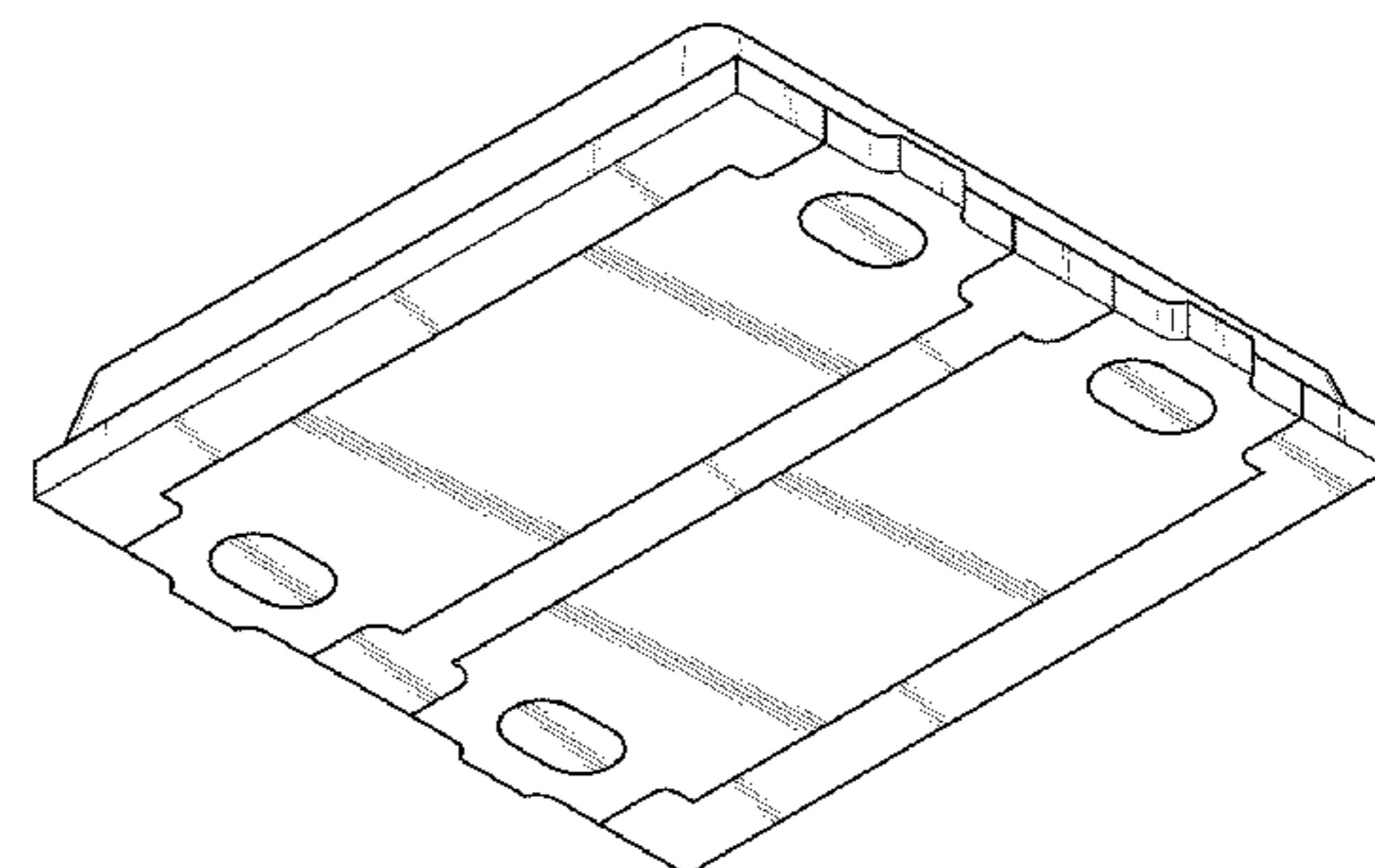
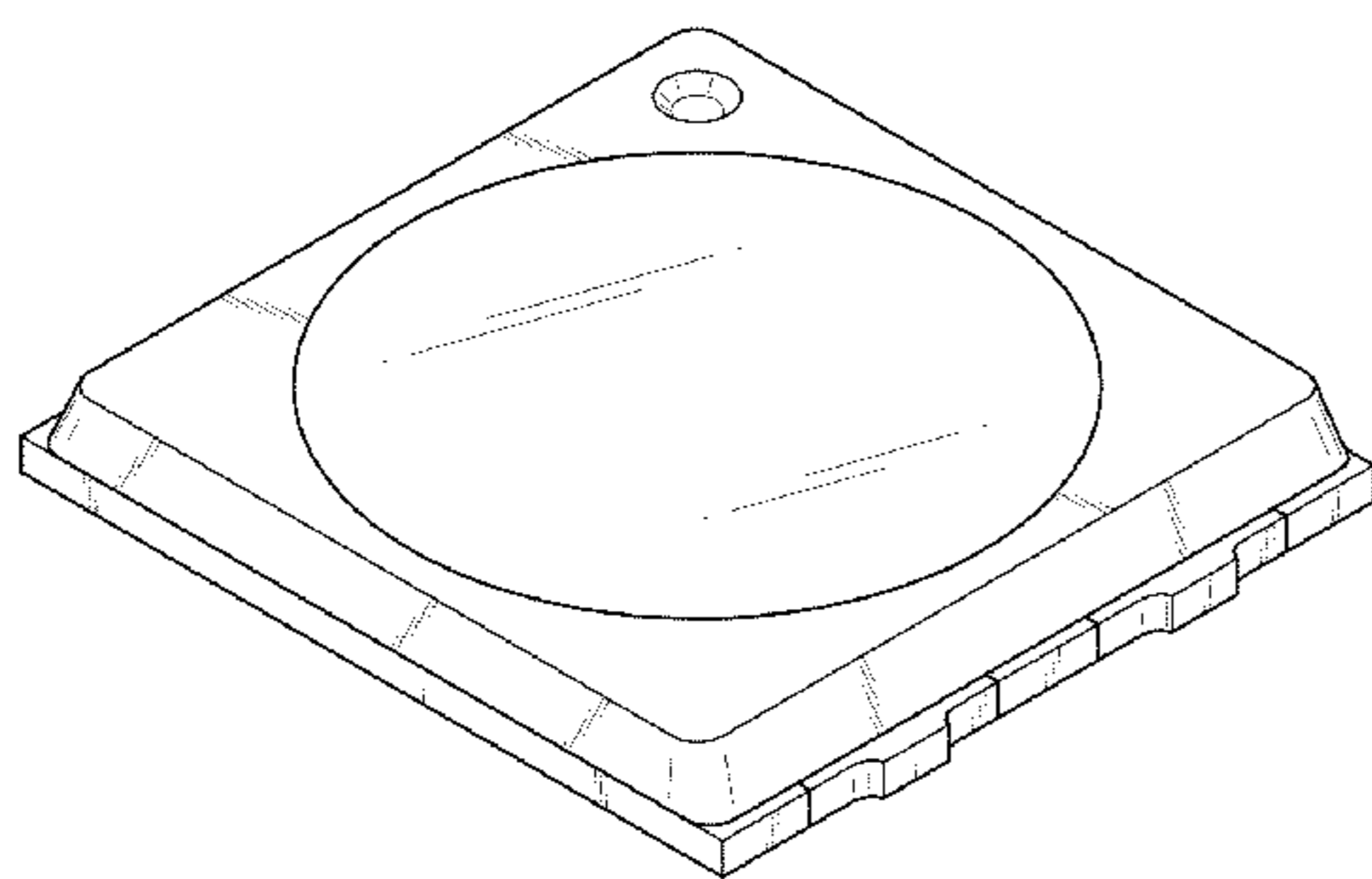
(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown and described.

**DESCRIPTION**

FIG. 1 is a front perspective view of a light emitting diode package showing the new design;  
FIG. 2 is another perspective view thereof;  
FIG. 3 is a front elevational view thereof;  
FIG. 4 is a rear elevational view thereof;  
FIG. 5 is a left side elevational view thereof;  
FIG. 6 is a right side elevational view thereof;  
FIG. 7 is a top plan view thereof; and,  
FIG. 8 is a bottom plan view thereof.

**1 Claim, 8 Drawing Sheets**



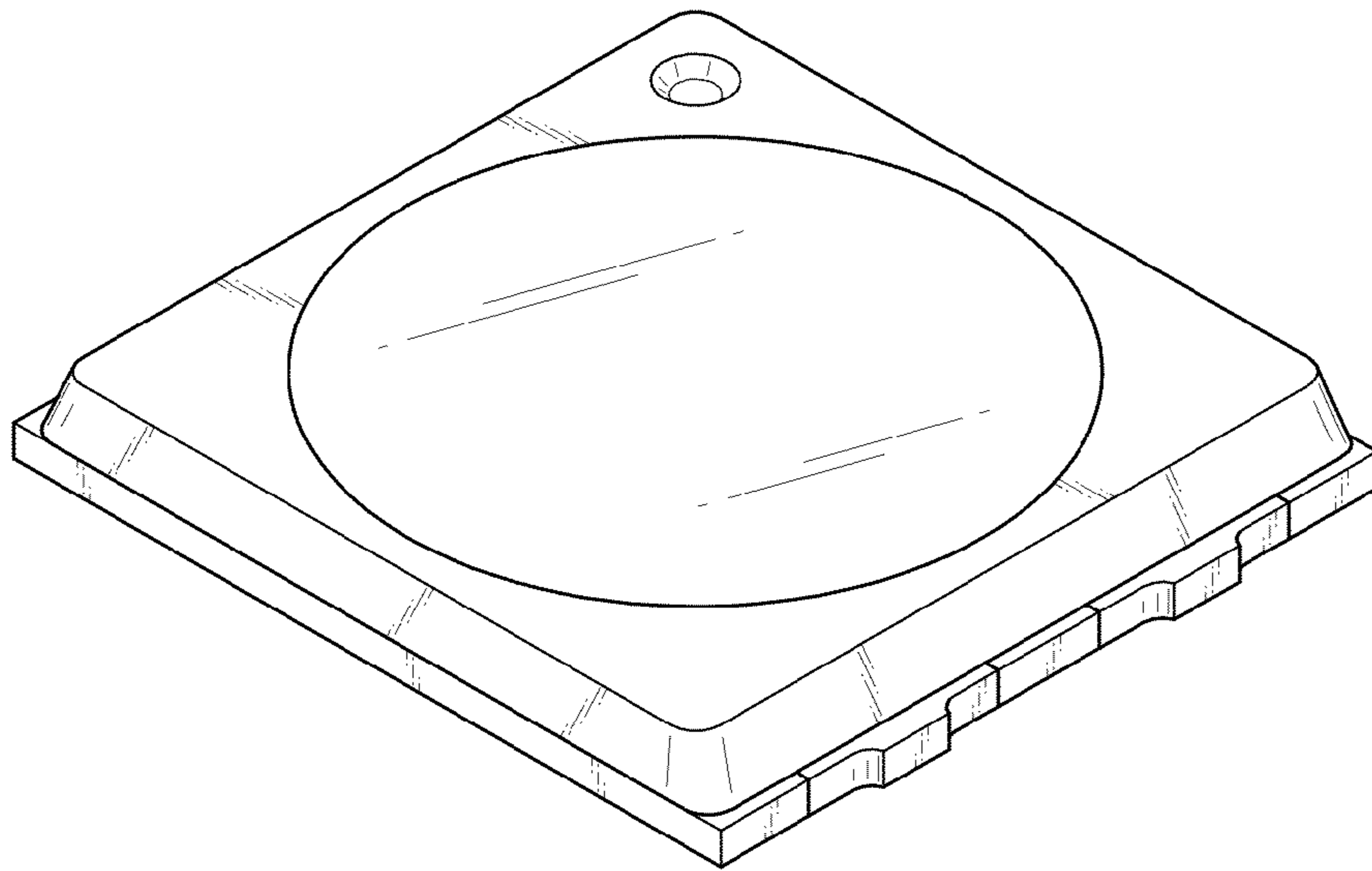


FIG.1

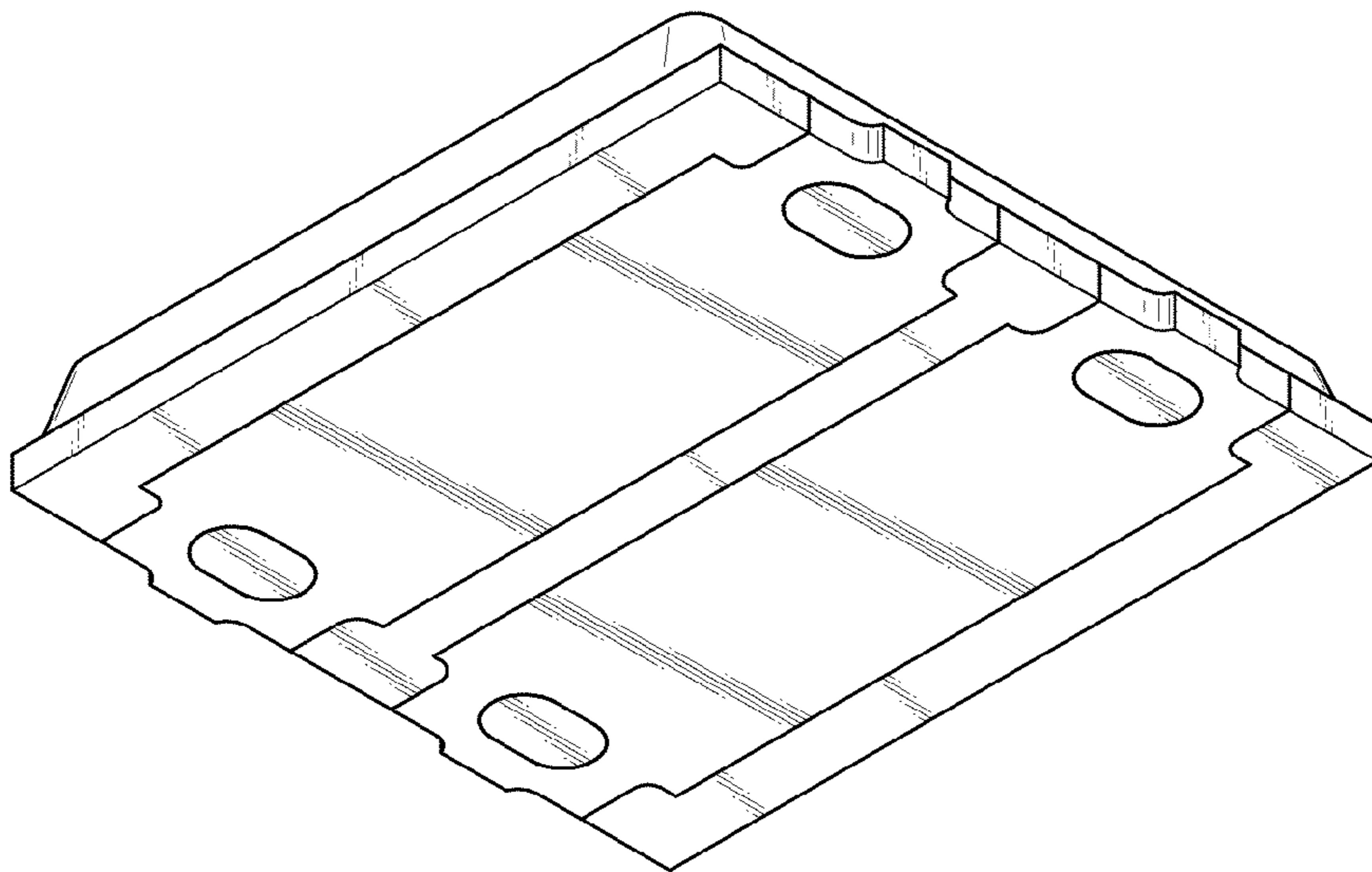


FIG.2

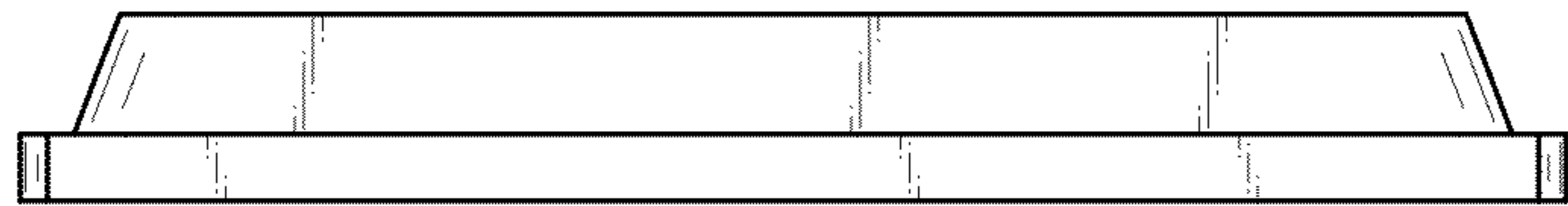


FIG.3



FIG.4

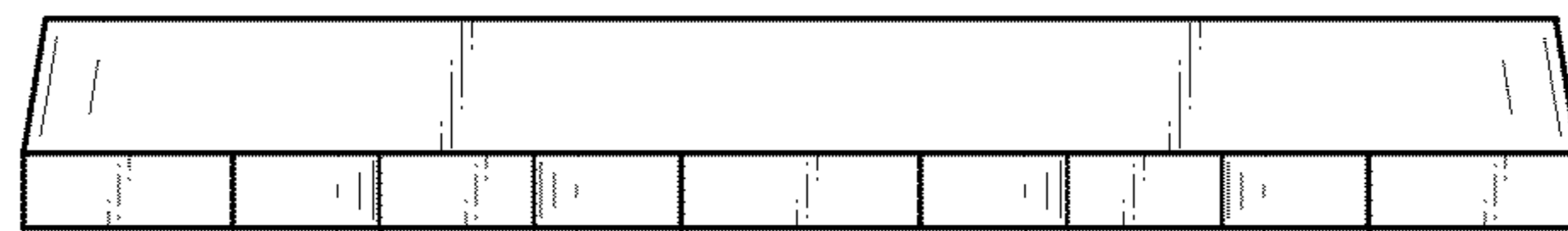


FIG.5

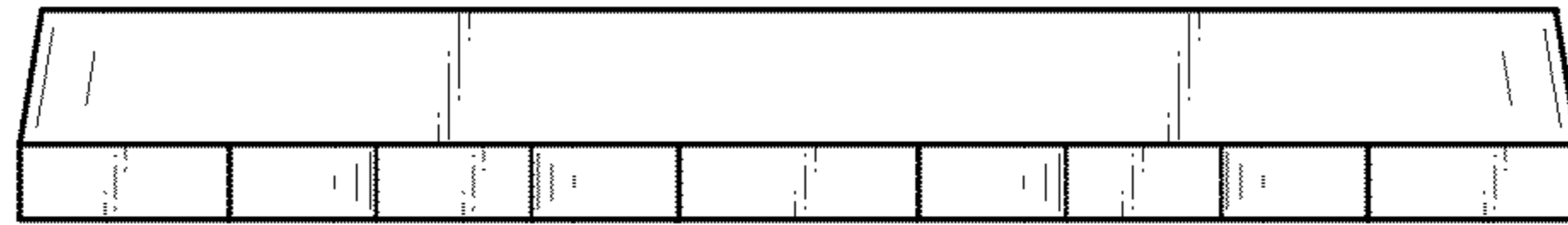


FIG.6

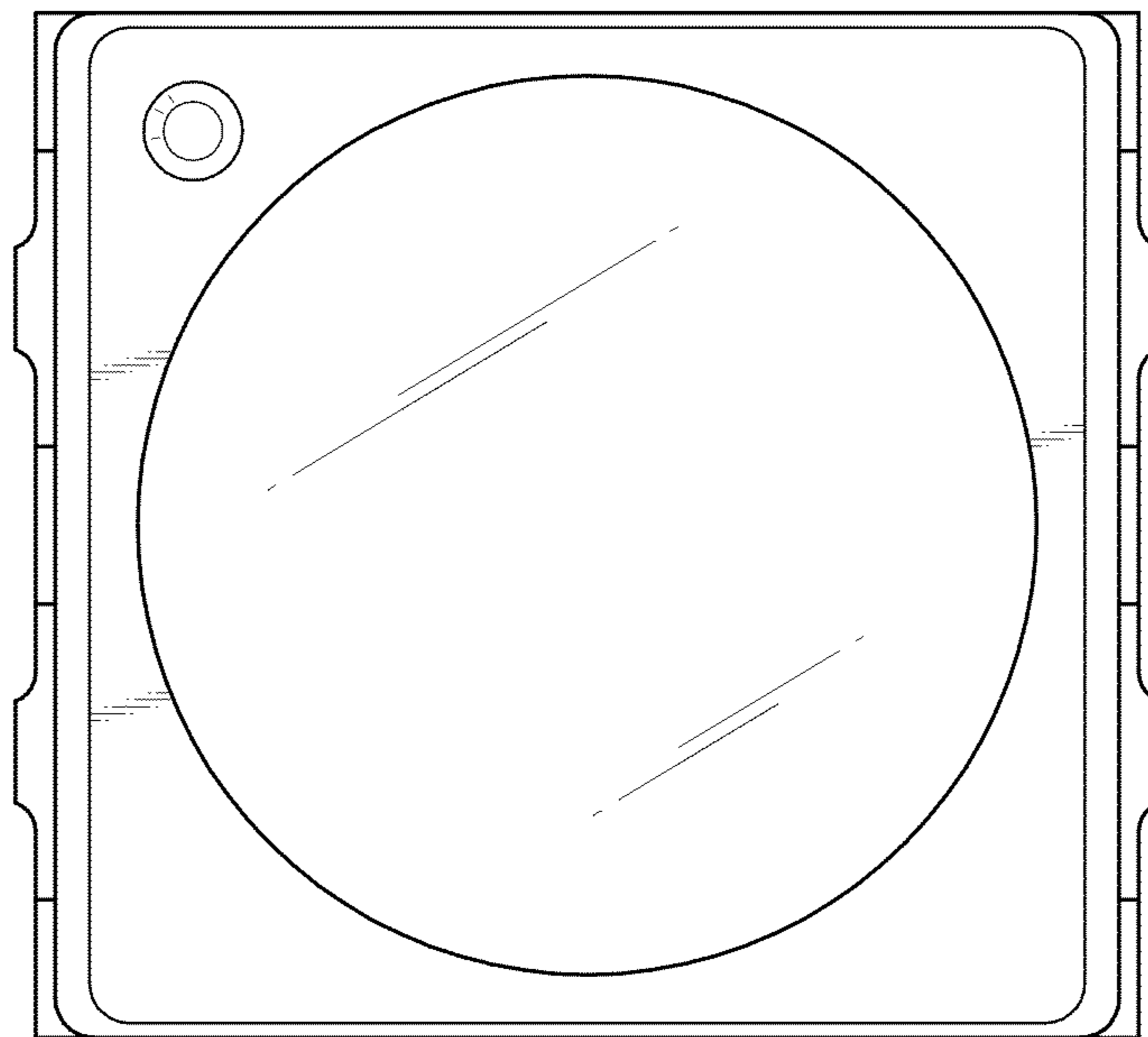


FIG. 7



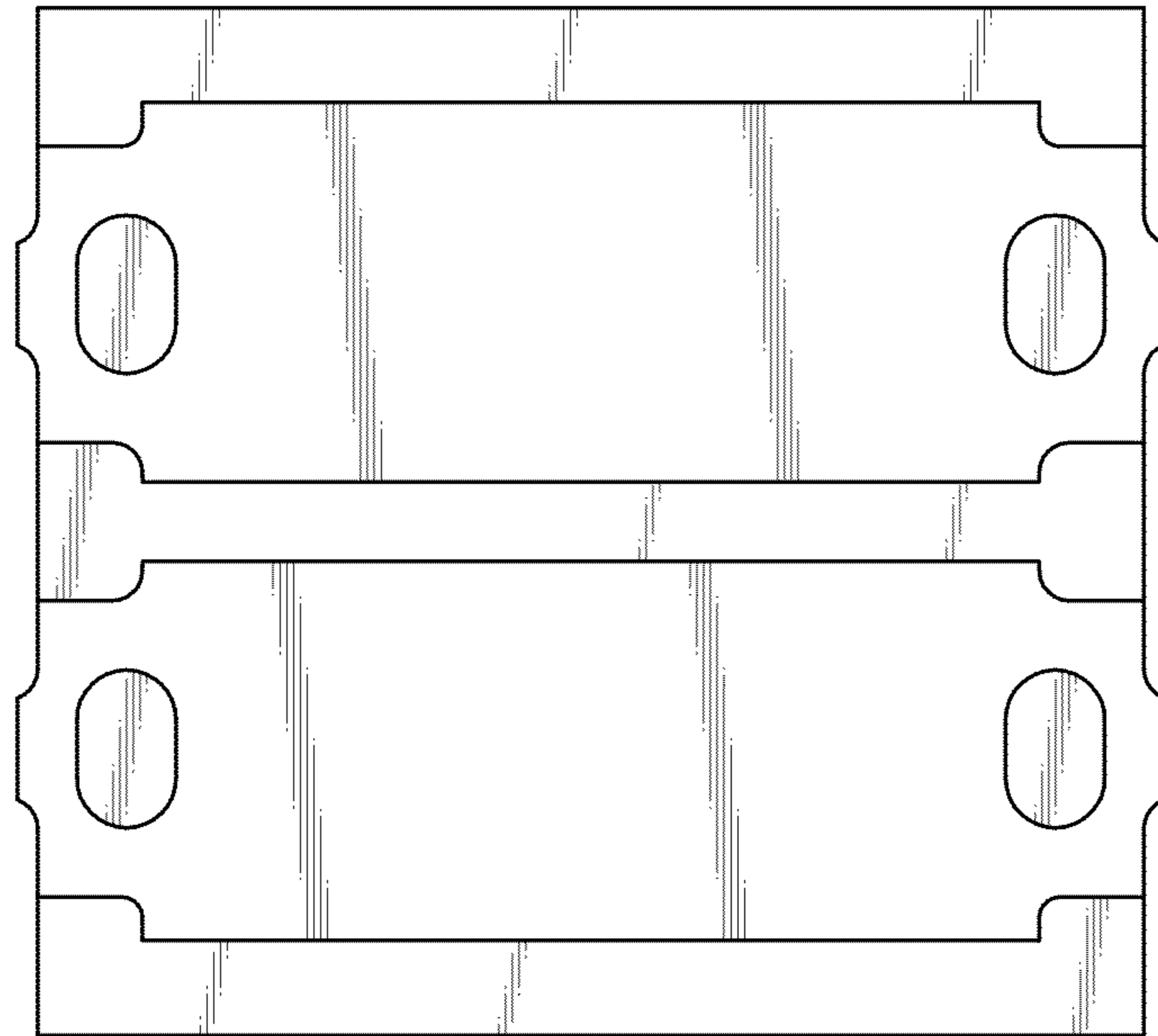


FIG.8